

2027 2nd International Conference on Electromagnetic Engineering & Microwave Systems

June 11-13, 2027 **Hangzhou, China**

EEMS 2027

www.iceems.org

Taking place from June 11 to 13, 2027 2nd International Conference on Electromagnetic Engineering & Microwave Systems (EEMS) will be held in Hangzhou, China. Co-sponsored by Yangtze Delta Region Academy of Beijing Institute of Technology (Jiaxing), Zhejiang University, Hangzhou Dianzi University, and Ningbo University, the conference aims to fully leverage Hangzhou's unique strengths in fostering innovation, creating a world-class international exchange platform that brings together global academics, industry leaders, and technology innovators. It will serve as a dynamic venue for sharing cutting-edge insights, building cross-border collaboration networks, and driving technological advancements in the fields of electromagnetic engineering and microwave systems.

CALL FOR PAPERS:

Track 5: Advanced RF Integration and Packaging Technologies

Track Chair:



Assoc. Prof. Shiyan Wang
Nanjing Normal University, China

RF Integration Technologies in 3D-IC

RF Design for System-in-Package (SiP)

Interconnection Technologies for Multi-Chip Modules (MCM)

RF Interconnection Design for TSV/TGV

EMC Design for RF Chiplet Integration and Packaging

Heterogeneous Integration RF Technologies

Thermal Management for RF Chiplet Packaging

Electromagnetic Protection for RF Front-ends

Millimeter-Wave Packaging and Antenna Integration

More information about topics, please visit: *https://www.iceems.org/cfp.html*

SUBMISSION

The manuscript in double-column format should have at least 4 full pages and up to 10 pages. If it exceeds 5 pages, the extra page(s) will be charged. Manuscripts must be written in English and follow the instructions at Manuscript Formatting and Templates. Submission system: *http://easychair.org/conferences/?conf=eems2027*

PUBLICATION

All submissions will be sent for double-blind review. Accepted papers with registration and presentation will be published in Conference Proceedings.

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IMPORTANT DATES

Submission Deadline: January 10th, 2027
Notification Date: February 10th, 2027
Registration Deadline: February 25th, 2027
Camera Ready: February 25th, 2027

CONTACT US

Conference secretary: Ms. Sia Liu
Email Address: eems_conf@163.com

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